Probe Cards for Automotive–
and Mixed Signal ICs

Applications characterised by a combination of logic circuitry and power outputs sharing the same die give special challenges for probe cards design and manufacturing – high density, fine pitch bond pads for the logic part in combination with hefty currents to be tested going up to several Amperes.

T.I.P.S.' cantilever probe cards are specifically designed to address the requirements of these applications – both in single die as well as in multi-die configurations.

- FEM designed and tested probe shapes yield very robust probe cards with excellent low contact resistance and a long lifetime.

- SmartClamp probes protection technology allows safe testing of highest currents up to 200 Amps.

- A temperature range of our probe cards from – 40 °C to 175°C allows to cope with the stringent test requirements of ICs for the automotive industry.